

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 03-002, GB10 POM copolymer Injection molding type, reinforced with ca. 10 % glass spheres; high resistance to thermal and oxidative degradation. UL-registration in natural and a thickness more than 0.81 mm, in black and a thickness more than 1.5 mm, as UL94 HB, temperature index UL 746 B for a thickness of 2 mm, electrical 105 °C, mechanical 95 °C (tensile impact) and 100 °C (tensile). Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: for low-warpage molded parts with higher rigidity and hardness. FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA)

Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load	9 190 2.16		ISO 1133
Moulding shrinkage, parallel Moulding shrinkage, normal [1]: @ 195°C	2.0 ^[1] 1.7 ^[1]		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [C]: Calculated	7.5 17 3000 2800 1500 60 60 4 4	MPa % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA ISO 2039-1
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel		°C E-6/K	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Thermal conductivity of melt Specific heat capacity of melt		W/(m K) J/(kg K)	ISO 22007-2 ISO 22007-4





HOSTAFORM®

Flammability				
Burning Behav. at 1.5mm nom. thickn. Thickness tested			class mm	IEC 60695-11-10 IEC 60695-11-10
Burning Behav. at thickness h			class	IEC 60695-11-10
Thickness tested		0.81	mm	IEC 60695-11-10
UL recognition		yes		UL 94
Electrical properties				
Relative permittivity, 100Hz		4.3		IEC 62631-2-1
Relative permittivity, 1MHz		4.1		IEC 62631-2-1
Dissipation factor, 100Hz Dissipation factor, 1MHz		150 60	E-4 E-4	IEC 62631-2-1 IEC 62631-2-1
Volume resistivity			Ohm.m	IEC 62631-3-1
Surface resistivity		1E14		IEC 62631-3-2
Electric strength			kV/mm	IEC 60243-1
Comparative tracking index		600		IEC 60112
Physical/Other properties				
Humidity absorption, 2mm		0.15		Sim. to ISO 62
Water absorption, 2mm		0.8		Sim. to ISO 62
Density		14/0	kg/m³	ISO 1183
Injection				
Drying Recommended		no		
Drying Temperature		100		
Drying Time, Dehumidified Dryer Processing Moisture Content		3 - 4 ≤0.2		
Melt Temperature Optimum		200		
Min. melt temperature		190		
Max. melt temperature		210		
Screw tangential speed		≤0.3		
Mold Temperature Optimum		100	°C °C	
Min. mould temperature Max. mould temperature		120		
Hold pressure range		60 - 120		
Back pressure			MPa	
Ejection temperature		140	°C	
Characteristics				
Processing	Injection Moulding			
Delivery form	Pellets			
Additives	Release agent			

Special characteristics

Low Warpage





HOSTAFORM®

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

Automotive

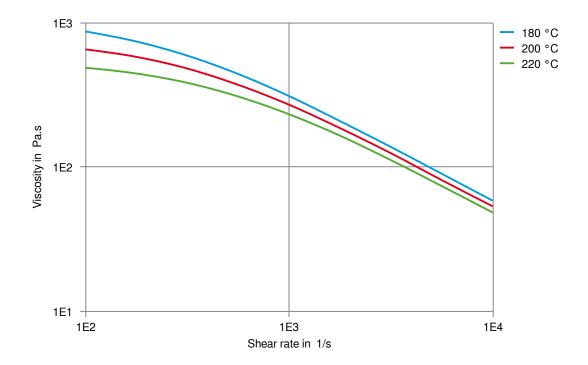
OEM Continental STANDARD TST N 055 54.13





HOSTAFORM®

Viscosity-shear rate

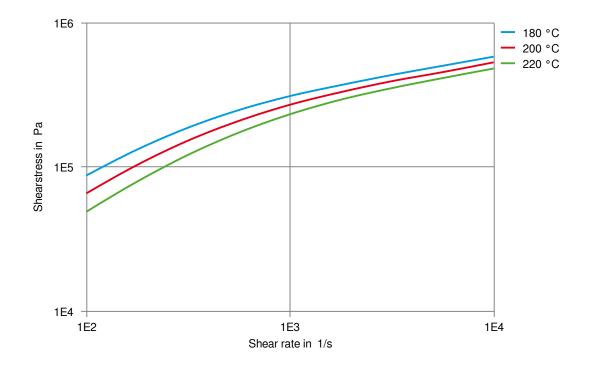






HOSTAFORM®

Shearstress-shear rate



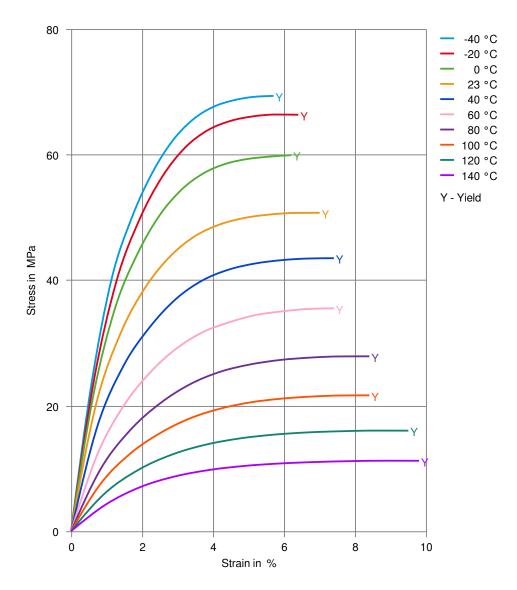




HOSTAFORM® C 9021 GV3/10

HOSTAFORM®

Stress-strain

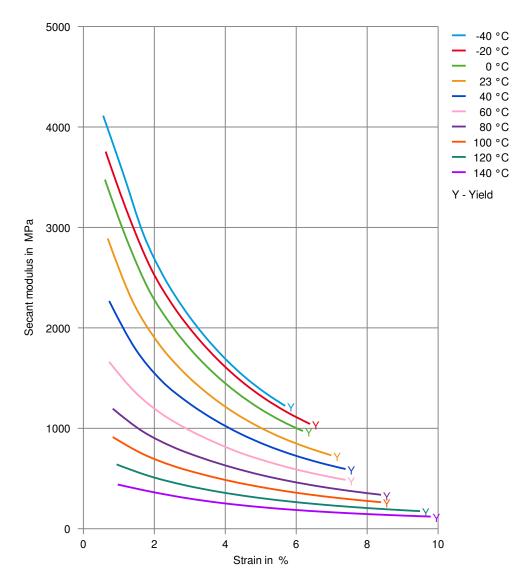






HOSTAFORM®

Secant modulus-strain



Printed: 2025-05-30

Page: 7 of 7

Revised: 2024-07-16 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication as a promise or guarantee of specific properties of our groucts. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to he lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material inductions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for addi

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.